



# KY8030-3

## The Industry's **Fastest True 3D Solder Paste Inspection Solution**

The KY8030-3 is back, faster than ever using Koh Young's 3D dual-inspection technology to eliminate critical shadow problems while enhancing productivity and speeding up the production process.



Unmatched Inspection Speed  
with Guaranteed Best Accuracy



Active Warp Compensation



Automated Solder Paste  
Dispensing: Auto-Rework



KSMART Solutions:  
True 3D Measurement-based  
Process Control System



Zero-defect through AI-Powered  
Koh Young Process Optimizer(KPO)





## Unmatched Inspection Speed with Guaranteed Best Accuracy

- The KY8030-3 blends Koh Young's pioneering technologies with an inspection speed of 91.2cm<sup>2</sup>/sec. The combination of this system's throughput and accuracy makes the KY8030-3 suitable across a vast range of applications. The latest options makes this system twice as fast as its predecessor with guaranteed measurement accuracy.



**KY8030-3**



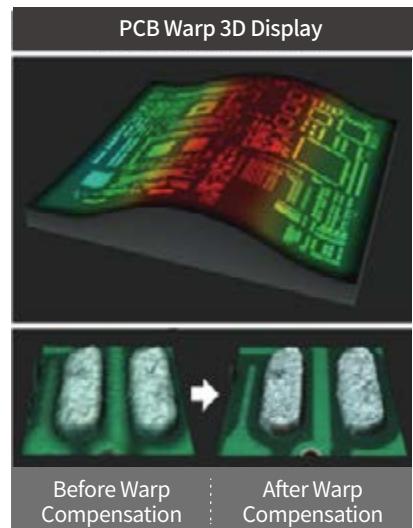
## Active Warp Compensation

### Z-tracking 3D compensation

The unique Koh Young warp compensation technology actively calculates and detects any substrate warpage. Using its exclusive 3D imaging and algorithms, Koh Young considers multiple elements like slope, stretch, twist, bow, and shrinkage to guarantee an accurate measurement and to meet the ultimate inspection system criteria.

### Pad-referencing 2D compensation (optional)

Real-time, automatic reference teaching uses IR lighting to compensate for non-linear inspection challenges by analyzing the PCB pad locations against the ideal PCB stencil design defined in the CAD file.



## Automated Solder Paste Dispensing: Auto-Rework

- KY8030-3 dispenses solder paste automatically as an optional add-on solution. The high-precision and user-friendly dispensing system helps eliminate costly mistakes due in large part to insufficient solder in open joints, lean fillets, and weak joints. The automatic dispensing option reduces operational costs, improves line efficiency, and strengthens profitability by eliminating board scrap and rework. Once Koh Young's SPI is configured with the Auto-Rework option, it becomes more than an inspection system. It becomes a true process optimizer.

Test Results		Small Sized Pad		Test Results		BGA Pad	
		Before				Before	
		Volume	30.24 %			Volume	22.4 %
		Height	86.68 um			Height	51.86 um
		Area	31.4 %			Area	38.87 %
		Offset X	0.001 mm			Offset X	-0.001 mm
		Offset Y	-0.008 mm			Offset Y	0.004 mm
		After				After	
		Volume	78.38 %			Volume	74.64 %
		Height	92.26 um			Height	71.71 um
		Area	76.46 %			Area	93.68 %
		Offset X	0.001 mm			Offset X	-0.001 mm
		Offset Y	-0.005 mm			Offset Y	0.004 mm

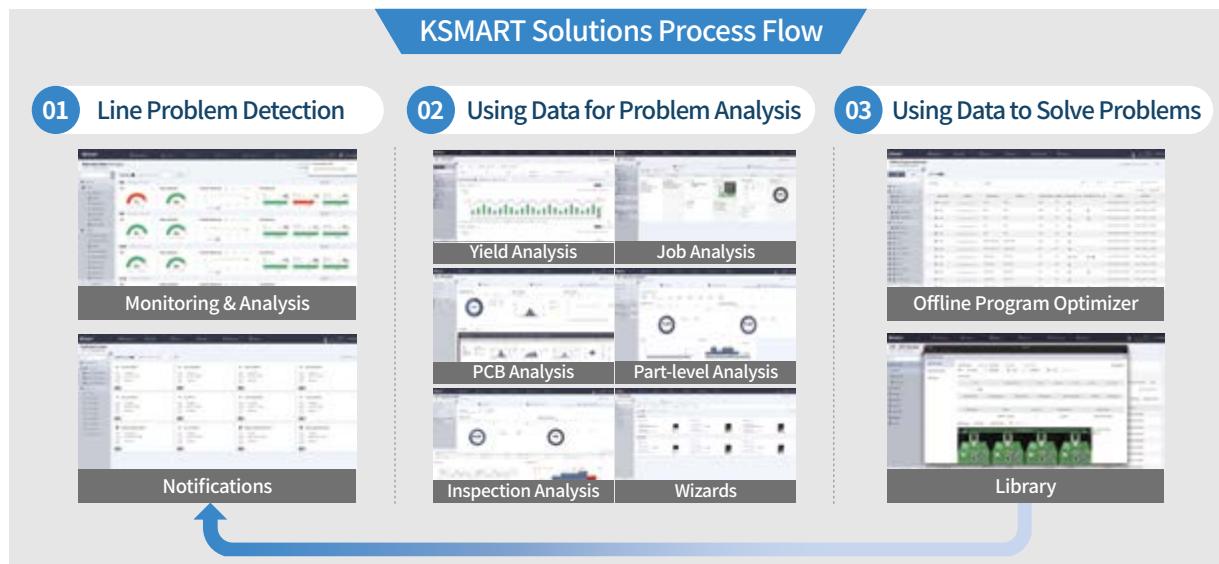


## The Gateway to a Smart Factory

- Koh Young pioneered True 3D measurement technology 20 years ago to create a zero-defect future. This gave rise to KSMART Solutions and its continuous efforts to leverage data and connectivity.
- KSMART Solutions uses Artificial Intelligence to help automate process control while focusing on data management, analysis, and optimization. It collects data from across the factory line for defect detection, real-time optimization, enhanced decisions, and traceability to improve metrics, increase quality, and lower costs by eliminating variance, false calls, and escapes.

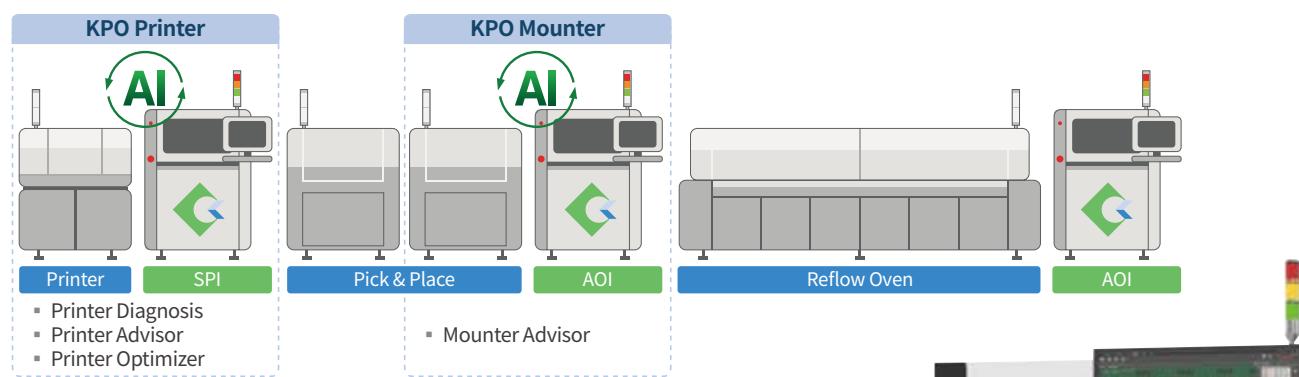
### KSMART Solutions: True 3D Measurement-based Process Control System

- Converts data into knowledge for effective and quality-driven actions
- Delivers an AI-powered process analysis and optimization tool
- Achieves an autonomous process optimization facility



### Zero-defect through AI-Powered Koh Young Process Optimizer (KPO)

- Koh Young is driven to help customers achieve a Zero-defect print process scenario. The AI-powered Koh Young Process Optimizer (KPO) solution automatically exercises complex algorithms to develop and implement print process improvements. By actively monitoring the print process, KPO sends operators real-time performance diagnostics and threshold alerts – it even implements process change automatically. KPO ensures real-time print process reliability without dedicated experts.



"We evaluated many inspection machines on the market and Koh Young proved to be the most reliable. The software was very stable and implementation was quick and easy. The machine caught defects that none of the other competitors could."

- Global EMS Company

# Must-check Requirements of a 3D SPI System

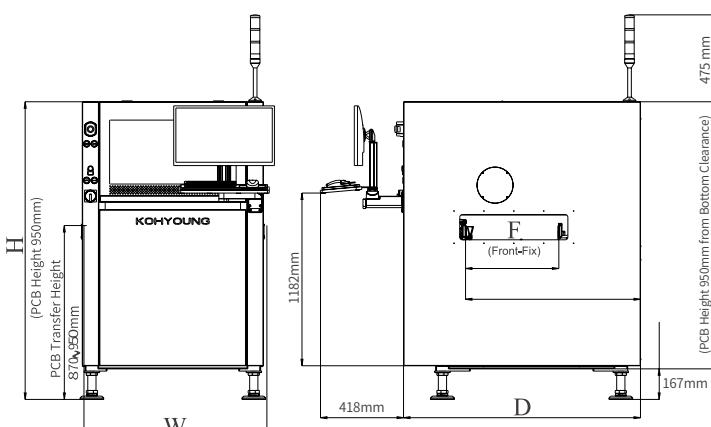
Requirements				Solutions							
Solution to shadow problem				3D shadow free moiré technology & dual projection							
Real-time PCB warp compensation (2D + 3D solution)				Active warp compensation (Z-tracking & pad-referencing (Optional))							
User-friendly operation				Renewal GUI, real color 3D image							
Whole-board Foreign Material Inspection (WFMI)				3D foreign material inspection							
Inspection Task	Metrology Capability	Volume, area, height, offset, bridging, shape deformity, paste offset, coplanarity									
Types of Defects	Insufficient, excessive, missing paste, bridging, shape deformity, paste offset, coplanarity										
Inspection Performance	Model	Camera	Pixel Resolution	Full Speed Inspection Speed	Min. Distance between Pads	Max. Inspection Height					
KY8030-3 (HS)	8M	20µm 15µm 10µm	91.2cm <sup>2</sup> /sec (0.35Sec/FOV) 53.5cm <sup>2</sup> /sec (0.33Sec/FOV) 23.8cm <sup>2</sup> /sec (0.33Sec/FOV)	20 µm: 200 µm / 7.9 mils 15 µm: 150 µm / 5.9 mils 10 µm: 100 µm / 4.0 mils	450 µm / 17.7 mils						
KY8030-3			20µm 15µm 10µm	47.1cm <sup>2</sup> /sec (0.34Sec/FOV) 28.1cm <sup>2</sup> /sec (0.32Sec/FOV) 13.3cm <sup>2</sup> /sec (0.30Sec/FOV)							
Illumination			IR-RGB Led Dome Styled Illumination								
Z Resolution			0.37 µm / 0.01 mils								
Height Accuracy (on KY Calibrated Target)			1 µm / 0.04 mils								
01005mm Inspection Capability			Gage R&R < 10% at 6 sigma ( $\pm 50\%$ Tolerance)								
Max. Inspection Size			< FOV								
Multi-Colored PCB Inspection		Possible									
Optional		4-Way Projection (Max. Inspection Height up to 2mm)									
PCB Handling	Conveyer Width Adjustment		Automatic								
	Conveyer Fix Type		Front / Rear fixed (Factory setting)								
Software	Supported Input Format		GERBER Data (274X, 274D), ODB++ (Optional)								
	Programming Software		ePM-SPI								
	Statistical Process Control Tool		SPC Plus (Histogram, X-bar & R-Chart, X-bar & S-Chart, Cp & Cpk, % Gage R&R / Real Time SPC & Multiple Display / SPC Alarm / Automatic Report from Remote Computer)								
	User-friendly Features		Library Manager & KYCAL (Auto Camera Calibration, Auto Illumination Calibration, Auto Height Calibration)								
	Operating System		WINDOWS 10 IoT ENTERPRISE LTSC 2019								
Add-On Solutions	- 1D & 2D Handy Barcode Reader - 1D & 2D Inline Barcode Reader - Auto-Verification - Auto-Rework*			- Offline Programming Station - ODB++ - SPC Plus for Remote Computer							
	- UPS - Integrated Calibration Target - Long Board Option - Review Station			- Panasonic APC Interface (FF/FB) - Panasonic iLNB Interface - Closed Loop Interface - IPC-CFX Interface							
				- KSMART Solutions (Monitoring and Analysis, Remote Access, Offline Program Optimizer, Link Data Analysis, Notification) - KPO Printer (Printer Diagnosis, Printer Advisor, Printer Optimizer) - Fuji Nexim Interface - iTAC Interface - ASYS OIC							

The above specifications are subject to change without notice.

\* Machine dimensions, PCB size, and clearance will change if the Auto-Rework option is selected.

	M		L		XL	
	Single Lane	Dual Lane	Single Lane	Dual Lane	Single Lane	Dual Lane
Max. PCB Size (X x Y)	330 x 330 mm (12.9 x 12.9 in)	330 x 580 mm (12.9 x 22.8 in)	510 x 510 mm (20.0 x 20.0 in)	510 x 580 mm (20.0 x 22.8 in)	850 x 690 mm (33.4 x 27.1 in)	850 x 580 mm (33.4 x 22.8 in)
Min. PCB Size	50 x 50 mm (1.9 x 1.9 in)		70 x 70 mm (2.7 x 2.7 in)			
PCB Thickness	0.4 ~ 4 mm (0.01 ~ 0.15 in)	0.4 ~ 5 mm (0.01 ~ 0.19 in)	0.6 ~ 8 mm (0.02 ~ 0.31 in)			
Max. PCB Weight	Standard : 2 kg (4.4 lbs), Heavy weight option : 5 kg (11.0 lbs)		10 kg (22.0 lbs)			
Machine Weight	550 kg (1212.5 lbs)	600 kg (1322.7 lbs)	600 kg (1322.7 lbs)	700 kg (1543.2 lbs)	850 kg (1873.9 lbs)	900 kg (1984.1 lbs)
Bottom Clearance	50 mm (1.9 in)					
Supplies	220 Vac ± 10%, 50/60Hz, 1 Phase, 5Kgf/cm <sup>2</sup> (0.45 MPa)					
W	820 mm (32.2 in)		1000 mm (39.3 in)		1350 mm (53.1 in)	
D	1265 mm (49.8 in)	1445 mm (56.8 in)	1265 mm (49.8 in)	1445 mm (56.8 in)	1445 mm (56.8 in)	
H	1627 mm (64.0 in)					

° Please contact us for more information about PCB Sizes.  
(The above specifications are subject to change without notice.)



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KY8030-3\_HQ\_S\_V01\_ENG\_202211